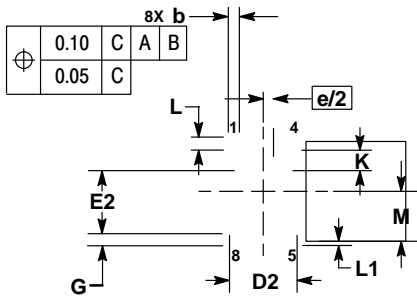
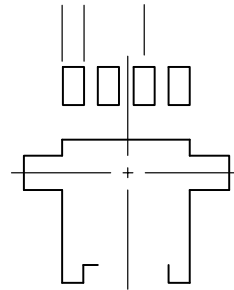


MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	---	0.05
b	0.23	0.30	0.40
c	0.15	0.20	0.25
D			
D1	2.95	3.05	3.15
D2	1.98	2.11	2.24
E			
E1	2.95	3.05	3.15
E2	1.47	1.60	1.73

e	0.65 BSC		
G	0.30	0.41	0.51
K	0.65	0.80	0.95
L	0.30	0.43	0.56
L1	0.06	0.13	0.20



SOLDERING FOOTPRINT* $\text{d} \leq \text{T} \leq \text{D} \leq 0.80 \text{ J} \leq \text{T} \leq \text{q}$



*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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